

**LINEAR TECHNOLOGY MATERIALS DECLARATION**

ltc1405cgn#pbf

(Engineering Calculation)

SSOP

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**TOTAL MASS (g) : 0.170832**

COMPONENT MATERIAL	VENDOR/ INDUSTRY NAMES	CONSTITUENT NAME	CAS NUMBER	CONSTITUENT MASS (g)	CONSTITUENT (PPM) OF MATERIAL	CONSTITUENT (PPM) OF TOTAL PKG.		
Active Device	Linear Technology	Silicon (Si)	7440-21-3	0.003112	1000000	18216.734375		
Die Coat	Dow Corning	Silicone	69430-27-9	0.000000	0	0		
Lead Frame	Cu	Copper (Cu)	7440-50-8	0.064009	975000	374689.90625		
		Iron (Fe)	7439-89-6	0.001576	24000	9225.44140625		
		Phosphorus (P)	7723-14-0	0.000020	300	117.074127197		
		Zinc (Zn)	7440-66-6	0.000046	700	269.270507812		
		Nickel (Ni)	7440-02-0	0.000000	0	0		
		Silicon (Si)	7440-21-3	0.000000	0	0		
		Magnesium (Mg)	7439-95-4	0.000000	0	0		
		Tin (Sn)	7440-31-5	0.000000	0	0		
<b>Lead Frame Total:</b>				<b>0.065651</b>	<b>1000000</b>	<b>384301.6875</b>		
Plating	PMI	Exter. Plating Pb	7439-92-1	0.000000	0	0		
		Exter. Plating Sn	7440-31-5	0.003749	1000000	21945.1445312		
		<b>External Plating Total:</b>				<b>0.003749</b>	<b>1000000</b>	<b>21945.1445312</b>
		Inter. Plating Ni	7440-02-0	0.000000	0	0		
		Inter. Plating Ag	7440-22-4	0.000525	1000000	3073.19580078		
<b>Internal Plating Total:</b>				<b>0.000525</b>	<b>1000000</b>	<b>3073.19580078</b>		
Die Attach	ELECTRICALLY CONDUCTIVE ADHESIVE	Silver (Ag)	7440-22-4	0.000933	750000	5461.50830078		
		Tin (Sn)	7440-31-5	0.000000	0	0		
		Lead (Pb)	7439-92-1	0.000000	0	0		
		Silica (SiO2)	60676-86-0	0.000000	0	0		
		Indium (In)	7440-74-6	0.000000	0	0		
		Metal Oxide		0.000000	0	0		
		Antimony (Sb)	7440-36-0	0.000000	0	0		
		Resin (EP)		0.000311	250000	1820.50280762		
<b>Die Attach Total:</b>				<b>0.001244</b>	<b>1000000</b>	<b>7282.01123047</b>		
Encapsulation	MULTI-AROMATIC RESIN Br/Sb FREE	Resin (EP)		0.009848	103000	57647.3007812		
		Bromine (Br)	40039-93-8	0.000000	0	0		
		Silica (SiO2)	60676-86-0	0.085571	895000	500907.46875		
		Antimony Trioxide (Sb2O3)	1309-64-4	0.000000	0	0		
		Metal Hydroxide		0.000000	0	0		
		Carbon Black (C)	1333-86-4	0.000191	2000	1118.0579834		
		<b>Encapsulation Total:</b>				<b>0.095610</b>	<b>1000000</b>	<b>559672.875</b>
Bond Wire Estimated	AFW/TANAKA/ Kn	Gold (Au)	7440-57-5	0.000941	1000000	5508.33740234		
					<b>TOTAL MASS (g) :</b>	<b>0.170832</b>		